

SPECIFICATIONS

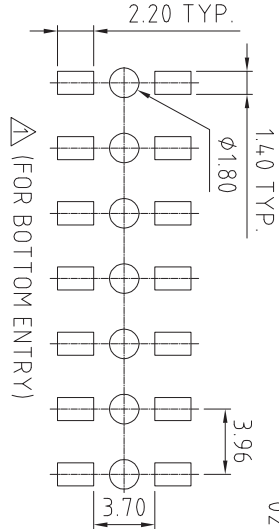
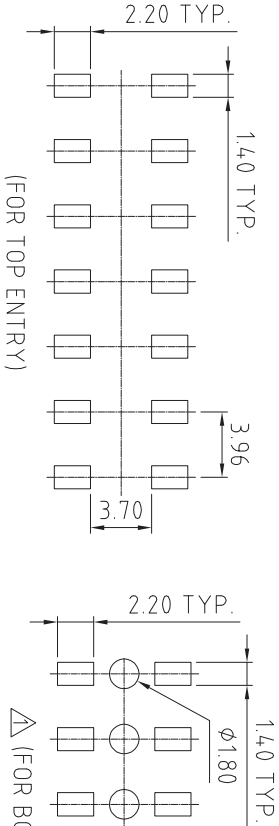
CURRENT RATING	7.9 AMP
INSULATOR RESISTANCE	1000 MEGOHMS MIN. Δ
CONTACT RESISTANCE	30m ohms MAX. Δ
DIELECTRIC WITHSTANDING	1000V AC/DC Δ
OPERATING TEMPERATURE	-40°C TO +105°C Δ
CONTACT MATERIAL	PHOSPHOR BRONZE
INSULATOR MATERIAL	LCP+30%GF, UL 94V-0
PLATING	MATT TIN OVER 30-50U" NICKEL
SOLDERABILITY	IR REFLOW: 280°C FOR 10 SEC WAVE: 250°C FOR 5-10 SEC MANUAL SOLDER: 380°C FOR 3-5 SEC

MATES WITH: - BB02-UG BB02-UK

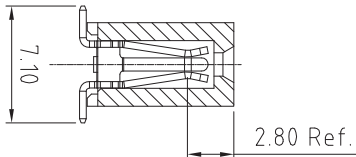
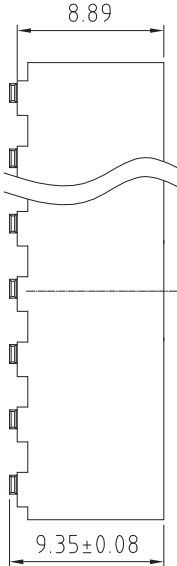
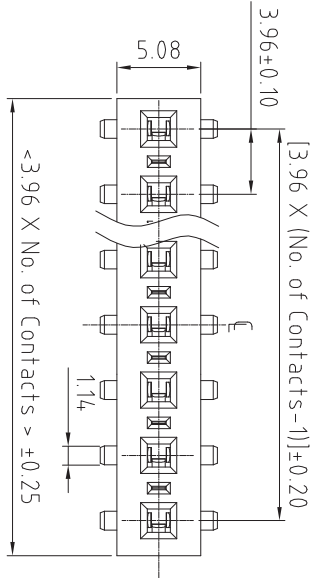
BB02-UH
BB02-UJ

NOTES:

1. GOLD FLASH PLATING IS AVAILABLE UPON REQUEST, PLEASE CONTACT US FOR MORE INFORMATION.
2. RECOMMENDED MATING PIN LENGTH FOR TOP ENTRY: 5.0MM.



(TOLERANCE: ±0.05)
RECOMMENDED PC BOARD LAYOUT



HOW TO ORDER

B B 0 2 - U T X X 2 - M 0 X - 0 0 0 0 0 0

NO. OF CONTACTS:

02 TO 24

CONTACT PLATING OPTIONS:

M = MATT TIN (STANDARD)

PACKAGE OPTIONS:

3 = TUBE / BOX

5 = TUBE + CAP

6 = TAPE & REEL

8 = TAPE & REEL + CAP

REV.	DATE & DRN	Scale:	3:1	THIRD ANGLE	Unstated Tolerances:	Material	SEE NOTE	Type:	BB02-UT
10	15/06/07 - CHC RELEASE	Drawn:	CHC		X ±0.30 X ±0.25 XX ±0.15 XXX ±0.10			Drawing Number:	BB02-UT
11	23/07/07 - NYW Δ ADD BOTTOM ENTRY LAYOUT	App'd:	XXXX	Title		NOT TO SCALE		Sheet	1 of 1
12	06/06/08 - CHC PLATING MODIFICATION.	Date:	24 JUL '14	Revision:	16	Unit:	mm	Drawing	© E and O E
13	25/12/08 - NYW DRAWING MODIFICATION.								
14	05/03/09 - NYW REMOVE OTHER PLATING OPTIONS. ADD NOTES 1.								
15	20/01/10 - NYW ADD NOTES 2.								
16	24/07/14 - NYW Δ AMEND SPECIFICATION.								

